



UPDATE CHANGE NOTIFICATION # 16710A

Generic Copy

Issue Date: 29-Feb-2012

TITLE: Copper wire bond for Micro 8 package in Seremban, Malaysia – FPCN Cancelled

PROPOSED FIRST SHIP DATE: N/A

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <alan.garlington@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or <ahmad.taufek@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <tomas.vaijter@onsemi.com>

DESCRIPTION AND PURPOSE:

The FPCN16710 was originally released on 1 Sept 2011 with an expiration date of 5-Dec-2011. This FPCN is now cancelled and the Micro 8 package will remain on the Gold Wire bond process. At some time in the future, a new FPCN may be issued to continue with this change.

 A General Announcement (GA#16200) was published on 1-29-09 regarding the ongoing Copper Wire bond conversion program at ON Semiconductor. This is a FPCN to notify customers of its plan to qualify Copper Wire (in place of Gold Wire) on the Micro 8 packages assembled at the Seremban, Malaysia assembly location. Reliability Qualification and full electrical characterization over temperature has now been completed on the designated package qualification vehicles.

List of affected General Parts:

LM258DMR2G	LP2951CDM-3.3R2G	MC34161DMR2G	NCV2904DMR2G
LM2903DMR2G	LP2951CDMR2G	MC34164DM-5R2G	NCV33064DM-5R2G
LM2904ADMR2G	MC33064DM-5R2G	NCP3335ADM150R2G	NCV431AIDMR2G
LM2904DMR2G	MC33161DMR2G	NCP3335ADM180R2G	NCV431BVDMR2G
LM2904VDMR2G	MC33164DM-3R2G	NCP3335ADM250R2G	TL431ACDMR2G
LM293DMR2G	MC33164DM-5R2G	NCP3335ADM280R2G	TL431AIDMR2G
LM358DMR2G	MC33178DMR2G	NCP3335ADM285R2G	TL431BCDMR2G
LM393DMR2G	MC33202DMR2G	NCP3335ADM300R2G	TL431BIDMR2G
LP2951ACDM-3.0RG	MC33762DM-2525RG	NCP3335ADM330R2G	TL431BVDMR2G
LP2951ACDM-3.3RG	MC33762DM-2828RG	NCP3335ADM500R2G	TL431CDMR2G
LP2951ACDMR2G	MC33762DM-3030RG	NCP3335ADMADJR2G	TL431IDMR2G
LP2951CDM-3.0R2G	MC34064DM-5R2G	NCV2903DMR2G	